MC14017B

Decade Counter

The MC14017B is a five–stage Johnson decade counter with built–in code converter. High speed operation and spike–free outputs are obtained by use of a Johnson decade counter design. The ten decoded outputs are normally low, and go high only at their appropriate decimal time period. The output changes occur on the positive–going edge of the clock pulse. This part can be used in frequency division applications as well as decade counter or decimal decode display applications.

- Fully Static Operation
- DC Clock Input Circuit Allows Slow Rise Times
- Carry Out Output for Cascading
- Divide–by–N Counting
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Capable of Driving Two Low–power TTL Loads or One Low–power Schottky TTL Load Over the Rated Temperature Range
- Pin–for–Pin Replacement for CD4017B
- Triple Diode Protection on All Inputs

MAXIMUM RATINGS (Voltages Referenced to V_{SS}) (Note 2.)

Symbol	Parameter	Value	Unit
V_{DD}	DC Supply Voltage Range	–0.5 to +18.0	V
V_{in}, V_{out}	Input or Output Voltage Range (DC or Transient)	–0.5 to V_{DD} + 0.5	V
I_{in}, I_{out}	Input or Output Current (DC or Transient) per Pin	±10	mA
P_D	Power Dissipation, per Package (Note 3.)	500	mW
T_A	Ambient Temperature Range	–55 to +125	°C
T_{stg}	Storage Temperature Range	–65 to +150	°C
T_L	Lead Temperature (8–Second Soldering)	260	°C

2. Maximum Ratings are those values beyond which damage to the device may occur.
3. Temperature Derating:
Plastic “P and D/DW” Packages: – 7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \leq (V_{in}$ or $V_{out}) \leq V_{DD}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.

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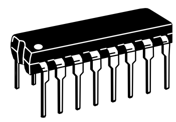
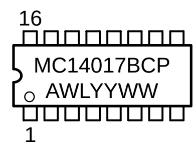
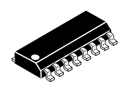
MARKING DIAGRAMS

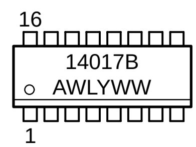


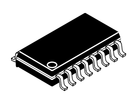
PDIP–16
P SUFFIX
CASE 648



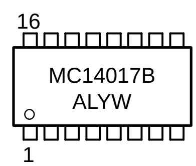


SOIC–16
D SUFFIX
CASE 751B





SOEIAJ–16
F SUFFIX
CASE 966



A	= Assembly Location
WL, L	= Wafer Lot
YY, Y	= Year
WW, W	= Work Week

ORDERING INFORMATION

Device	Package	Shipping
MC14017BCP	PDIP–16	2000/Box
MC14017BD	SOIC–16	48/Rail
MC14017BDR2	SOIC–16	2500/Tape & Reel
MC14017BF	SOEIAJ–16	See Note 1.
MC14017BFEL	SOEIAJ–16	See Note 1.

1. For ordering information on the EIAJ version of the SOIC packages, please contact your local ON Semiconductor representative.

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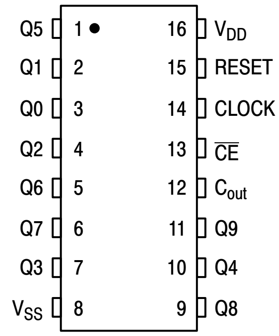
PIN ASSIGNMENT

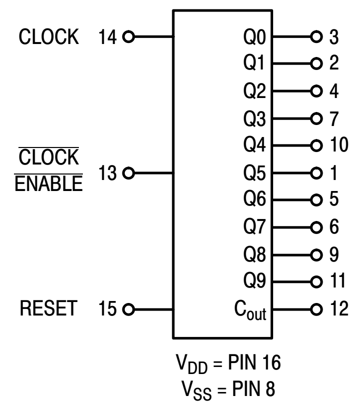


FUNCTIONAL TRUTH TABLE (Positive Logic)

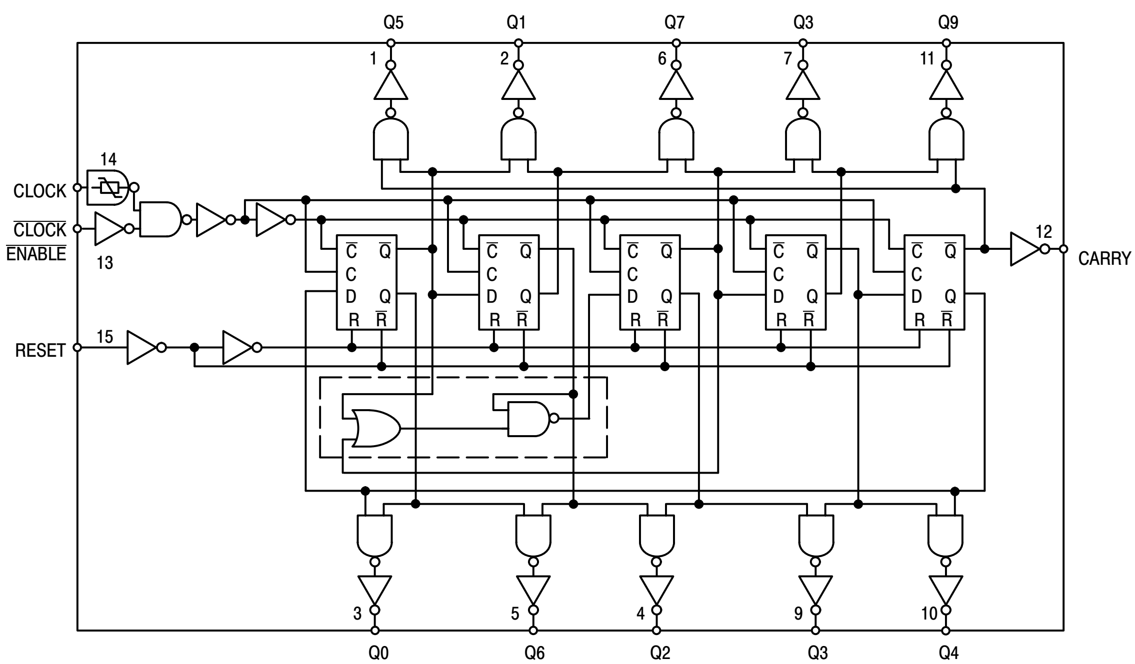
Clock	$\overline{\text{Clock}}$ Enable	Reset	Decode Output=n
0	X	0	n
X	1	0	n
X	X	1	Q0
↑	0	0	n+1
↓	X	0	n
X	↑	0	n
1	↓	0	n+1

X = Don’t Care. If n < 5 Carry = “1”, Otherwise = “0”.

BLOCK DIAGRAM



LOGIC DIAGRAM



ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

Characteristic	Symbol	V_{DD} Vdc	– 55°C		25°C			125°C		Unit
			Min	Max	Min	Typ [4.]	Max	Min	Max	
Output Voltage "0" Level	V_{OL}	5.0	—	0.05	—	0	0.05	—	0.05	Vdc
V_{in} = V_{DD} or 0		10	—	0.05	—	0	0.05	—	0.05	
		15	—	0.05	—	0	0.05	—	0.05	
"1" Level	V_{OH}	5.0	4.95	—	4.95	5.0	—	4.95	—	Vdc
V_{in} = 0 or V_{DD}		10	9.95	—	9.95	10	—	9.95	—	
		15	14.95	—	14.95	15	—	14.95	—	
Input Voltage "0" Level	V_{IL}									Vdc
(V_O = 4.5 or 0.5 Vdc)		5.0	—	1.5	—	2.25	1.5	—	1.5	
(V_O = 9.0 or 1.0 Vdc)		10	—	3.0	—	4.50	3.0	—	3.0	
(V_O = 13.5 or 1.5 Vdc)		15	—	4.0	—	6.75	4.0	—	4.0	
"1" Level	V_{IH}									Vdc
(V_O = 0.5 or 4.5 Vdc)		5.0	3.5	—	3.5	2.75	—	3.5	—	
(V_O = 1.0 or 9.0 Vdc)		10	7.0	—	7.0	5.50	—	7.0	—	
(V_O = 1.5 or 13.5 Vdc)		15	11	—	11	8.25	—	11	—	
Output Drive Current	I_{OH}									mAdc
(V_{OH} = 2.5 Vdc) Source		5.0	– 3.0	—	– 2.4	– 4.2	—	– 1.7	—	
(V_{OH} = 4.6 Vdc)		5.0	– 0.64	—	– 0.51	– 0.88	—	– 0.36	—	
(V_{OH} = 9.5 Vdc)		10	– 1.6	—	– 1.3	– 2.25	—	– 0.9	—	
(V_{OH} = 13.5 Vdc)		15	– 4.2	—	– 3.4	– 8.8	—	– 2.4	—	
(V_{OL} = 0.4 Vdc) Sink	I_{OL}	5.0	0.64	—	0.51	0.88	—	0.36	—	mAdc
(V_{OL} = 0.5 Vdc)		10	1.6	—	1.3	2.25	—	0.9	—	
(V_{OL} = 1.5 Vdc)		15	4.2	—	3.4	8.8	—	2.4	—	
Input Current	I_{in}	15	—	± 0.1	—	±0.00001	± 0.1	—	± 1.0	µAdc
Input Capacitance (V_{in} = 0)	C_{in}	—	—	—	—	5.0	7.5	—	—	pF
Quiescent Current (Per Package)	I_{DD}	5.0	—	5.0	—	0.005	5.0	—	150	µAdc
		10	—	10	—	0.010	10	—	300	
		15	—	20	—	0.015	20	—	600	
Total Supply Current [5.] [6.] (Dynamic plus Quiescent, Per Package) (C_L = 50 pF on all outputs, all buffers switching)	I_T	5.0	I_T = (0.27 µA/kHz) f + I_{DD}							µAdc
		10	I_T = (0.55 µA/kHz) f + I_{DD}							
		15	I_T = (0.83 µA/kHz) f + I_{DD}							

4. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
5. The formulas given are for the typical characteristics only at 25°C.
6. To calculate total supply current at loads other than 50 pF:

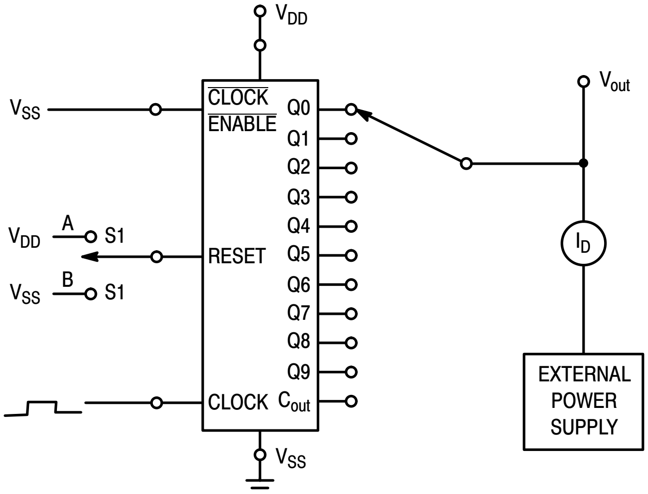
$$I_T(C_L) = I_T(50\ pF) + (C_L - 50)\ Vfk$$

where: I_T is in µA (per package), C_L in pF, V = (V_{DD} – V_{SS}) in volts, f in kHz is input frequency, and k = 0.0011.

SWITCHING CHARACTERISTICS (7.) (C_L = 50 pF, T_A = 25°C)

Characteristic	Symbol	V_{DD} Vdc	Min	Typ (8.)	Max	Unit
Output Rise and Fall Time	t_{TLH}, t_{THL}					ns
t_{TLH}, t_{THL} = (1.5 ns/pF) C_L + 25 ns		5.0	—	100	200	
t_{TLH}, t_{THL} = (0.75 ns/pF) C_L + 12.5 ns		10	—	50	100	
t_{TLH}, t_{THL} = (0.55 ns/pF) C_L + 9.5 ns		15	—	40	80	
Propagation Delay Time Reset to Decode Output	t_{PLH}, t_{PHL}					ns
t_{PLH}, t_{PHL} = (1.7 ns/pF) C_L + 415 ns		5.0	—	500	1000	
t_{PLH}, t_{PHL} = (0.66 ns/PF) C_L + 197 ns		10	—	230	460	
t_{PLH}, t_{PHL} = (0.5 ns/pF) C_L + 150 ns		15	—	175	350	
Propagation Delay Time Clock to C_{out}	t_{PLH}, t_{PHL}					ns
t_{PLH}, t_{PHL} = (1.7 ns/pF) C_L + 315 ns		5.0	—	400	800	
t_{PLH}, t_{PHL} = (0.66 ns/pF) C_L + 142 ns		10	—	175	350	
t_{PLH}, t_{PHL} = (0.5 ns/pF) C_L + 100 ns		15	—	125	250	
Propagation Delay Time Clock to Decode Output	t_{PLH}, t_{PHL}					ns
t_{PLH}, t_{PHL} = (1.7 ns/pF) C_L + 415 ns		5.0	—	500	1000	
t_{PLH}, t_{PHL} = (0.66 ns/pF) C_L + 197 ns		10	—	230	460	
t_{PLH}, t_{PHL} = (0.5 ns/pF) C_L + 150 ns		15	—	175	350	
Turn–Off Delay Time Reset to C_{out}	t_{PLH}					ns
t_{PLH} = (1.7 ns/pF) C_L + 315 ns		5.0	—	400	800	
t_{PLH} = (0.66 ns/pF) C_L + 142 ns		10	—	175	350	
t_{PLH} = (0.5 ns/pF) C_L + 100 ns		15	—	125	250	
Clock Pulse Width	$t_{w(H)}$	5.0	250	125	—	ns
		10	100	50	—	
		15	75	35	—	
Clock Frequency	f_{cl}	5.0	—	5.0	2.0	MHz
		10	—	12	5.0	
		15	—	16	6.7	
Reset Pulse Width	$t_{w(H)}$	5.0	500	250	—	ns
		10	250	125	—	
		15	190	95	—	
Reset Removal Time	t_{rem}	5.0	750	375	—	ns
		10	275	135	—	
		15	210	105	—	
Clock Input Rise and Fall Time	t_{TLH}, t_{THL}	5.0				—
		10		No Limit		
		15				
$\overline{\text{Clock Enable}}$ Setup Time	t_{su}	5.0	350	175	—	ns
		10	150	75	—	
		15	115	52	—	
$\overline{\text{Clock Enable}}$ Removal Time	t_{rem}	5.0	420	260	—	ns
		10	200	100	—	
		15	140	70	—	

7. The formulas given are for the typical characteristics only at 25°C.
8. Data labelled “Typ” is not to be used for design purposes but is intended as an indication of the IC’s potential performance.



	Output Sink Drive	**Output Source Drive**
Decode Outputs	(S1 to A)	Clock to desired outputs (S1 to B)
Carry	Clock to 5 thru 9 (S1 to B)	S1 to A
V_{GS} =	V_{DD}	$-V_{DD}$
V_{DS} =	V_{out}	$V_{out} - V_{DD}$

Figure 1. Typical Output Source and Output Sink Characteristics Test Circuit

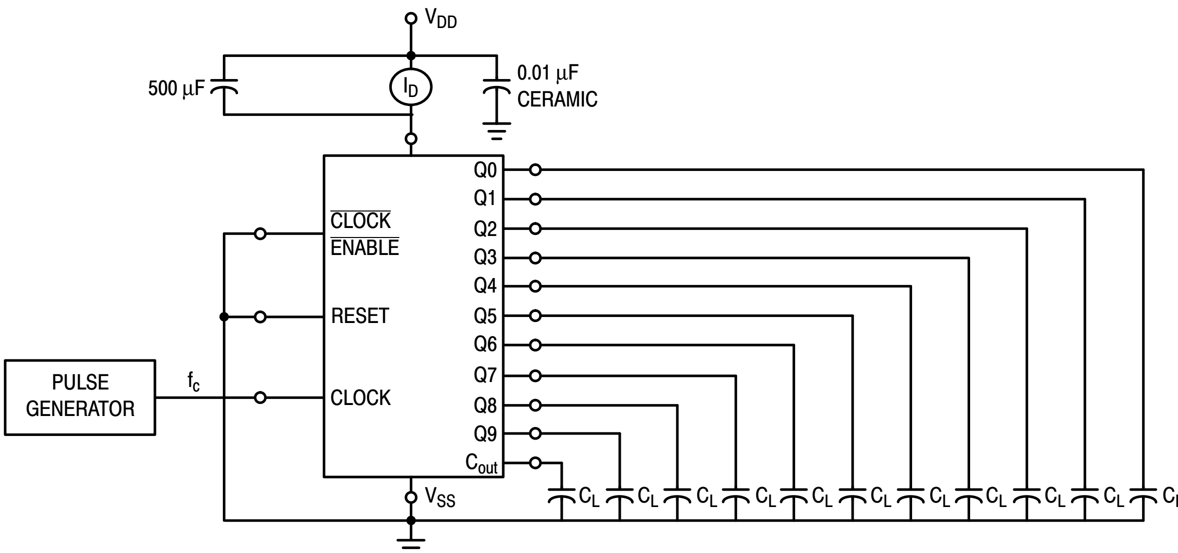


Figure 2. Typical Power Dissipation Test Circuit

APPLICATIONS INFORMATION

Figure 3 shows a technique for extending the number of decoded output states for the MC14017B. Decoded outputs are sequential within each stage and from stage to stage, with no dead time (except propagation delay).

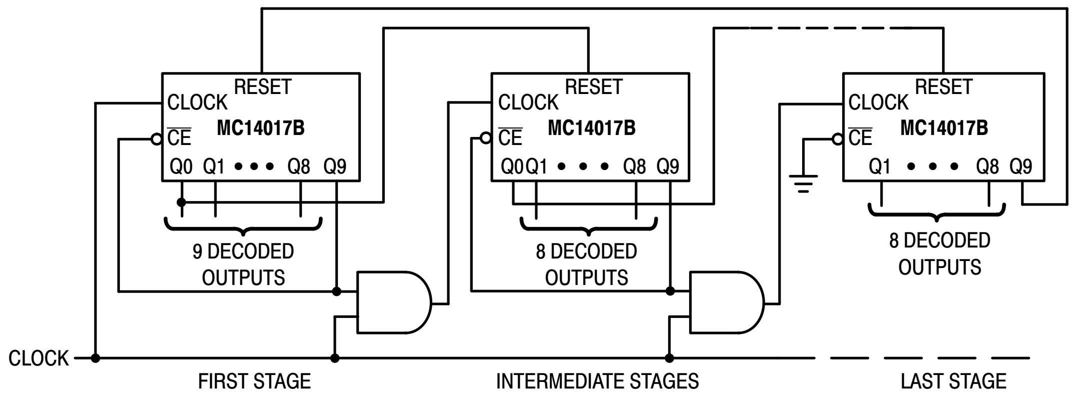


Figure 3. Counter Expansion

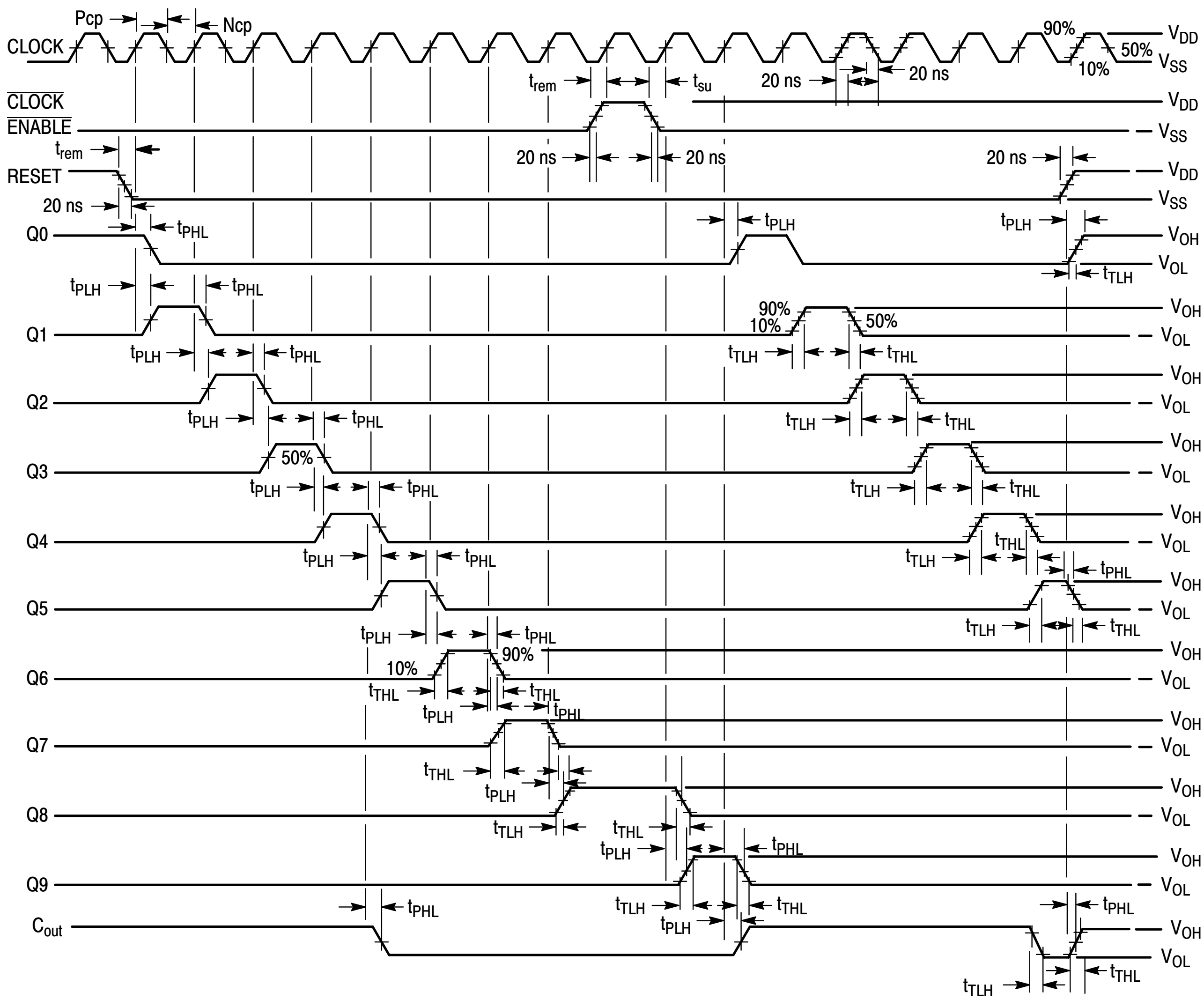
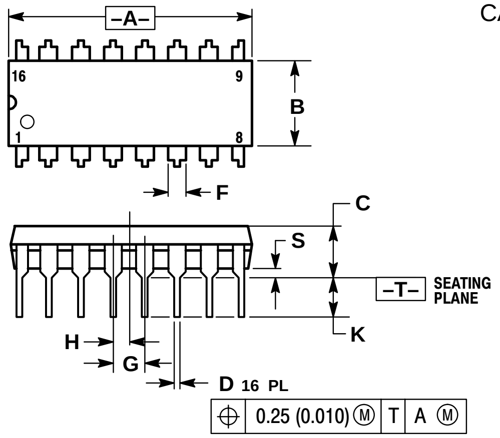
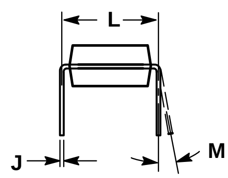


Figure 4. AC Measurement Definition and Functional Waveforms

PACKAGE DIMENSIONS

PDIP–16
P SUFFIX
PLASTIC DIP PACKAGE
CASE 648–08
ISSUE R

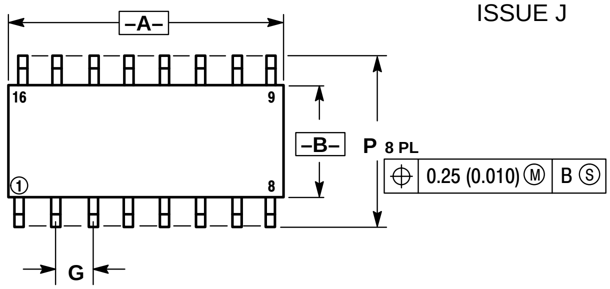


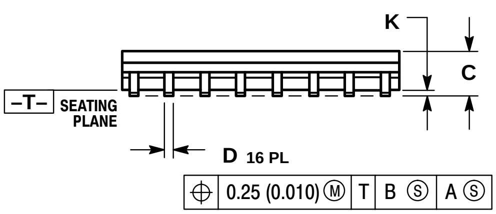


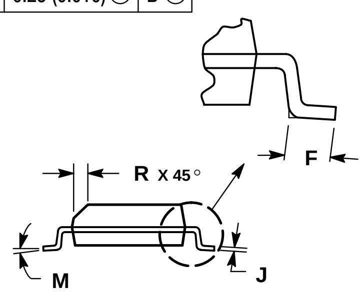
NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

SOIC–16
D SUFFIX
PLASTIC SOIC PACKAGE
CASE 751B–05
ISSUE J





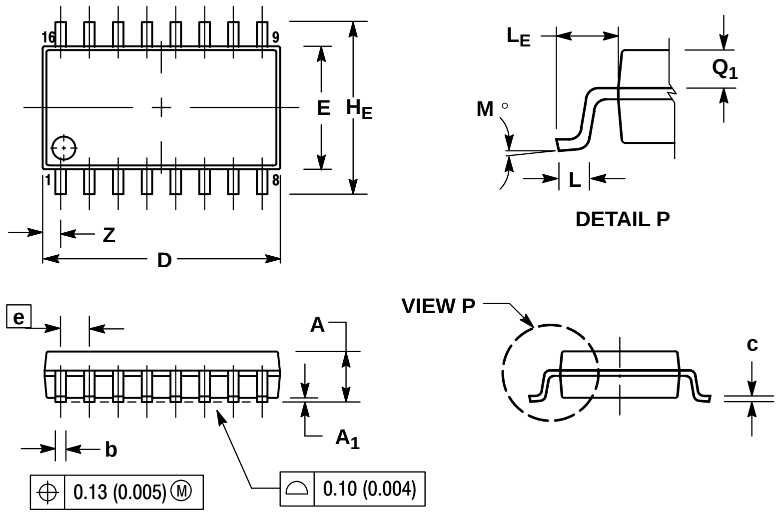


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

PACKAGE DIMENSIONS

SOEIAJ–16
F SUFFIX
PLASTIC EIAJ SOIC PACKAGE
CASE 966–01
ISSUE O



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	–––	2.05	–––	0.081
A_1	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H_E	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L_E	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10 °
Q_1	0.70	0.90	0.028	0.035
Z	–––	0.78	–––	0.031

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